SPECIFICATION

Product : Thermoelectric module

Part Number : HPE-288-10-08

1 . Scope

1—1 This specification is applied to Multicomp thermoelectric modules

1—2 Revision of these specifications is carried out after consent.

2 . Specification

2 - 1 Parameters

Parameters			Remarks
Internal resistance	5.0 Ω ± 10%		Note-1
Imax.	6.0 A		Note-2
Vmax.	36.0 V		Note-3
	Th=25℃		
Qmax.	123.5 W		Note-4
⊿Tmax.	69℃		Note-5
solder melting point	138 ℃		Note-6
Maximum. compress.	1MPa		Note-7

Note-1 Measured by AC 4-terminal method at 25℃.

Note-2 Maximum current at ⊿Tmax.

Note-3 Maximum voltage at ⊿Tmax.

Note-4 Maximum cooling capacity at Imax.,Vmax. and ⊿T = 0℃.

Note-5 Maximum temperature difference at Imax.,Vmax. and Q = 0W.

(Maximum parameters are measured in a vacuum 1.3P)

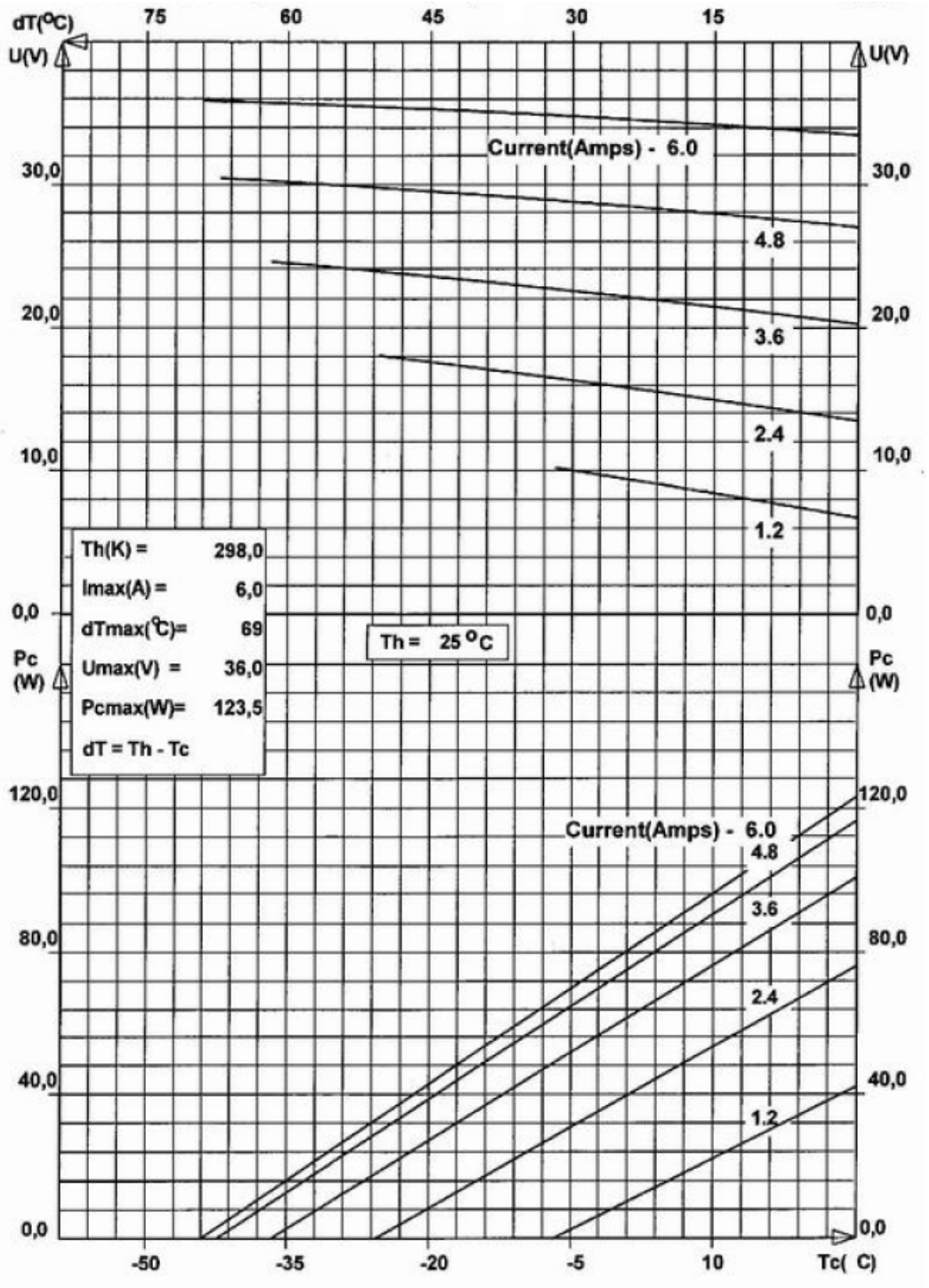
Note-6 The solder melting point of thermoelectric module

Note-7 Recommended maximum compression (not destruction limit)

2 -2 Recommendations:

- high cooling capacity from a small surface and long lifetime in power cycling applications with change of current polarity
- operation temperature up to 90°C for long lifetime; up to 110 degC for short periods
- with operation current close to 0.5 Imax extremely high COP (coefficient of performance possible)
- preferable application; high cooling capacity at high temperatures / cycling

2 - 3 Performance Graph (298K)



2 - 4 Performance Graph (323K)